Global Semiconductor Automatic Packaging Equipment Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global Semiconductor Automatic Packaging Equipment market size is expected to reach $ 2606 million by 2032, rising at a market growth of 6.7% CAGR during the forecast period (2026-2032).

In 2025, global Semiconductor Automatic Packaging Equipment production reached approximately 4450 units with an average global market price of around k US$360 per unit. Semiconductor Automatic Packaging Equipment is a specialized device used to package semiconductor chips (such as integrated circuits, sensors, etc.) into final products. Packaging is the final important step in the semiconductor manufacturing process, which places the manufactured chips inside the packaging shell and provides electrical connections and mechanical protection so that the chips can be safely and effectively used in various electronic devices. Fully automatic packaging equipment can achieve high automation in this process, thereby improving production efficiency, product quality, and reducing production costs.

The future main direction of Semiconductor Automatic Packaging Equipment will shift from traditional back-end capacity expansion toward competition in advanced packaging, heterogeneous integration, and high-yield automation capabilities. AI, high-performance computing, and high-bandwidth memory are driving upgrades in logic and memory packaging demand. TSMC’s annual report clearly identifies advanced packaging and three-dimensional stacking technologies such as CoWoS, InFO, and SoIC as key technologies supporting customer demand, indicating that equipment demand will increasingly focus on bonding, die attach, wafer-level packaging, inspection, handling, and process integration. From the perspective of equipment companies, ASMPT disclosed strong momentum in its advanced packaging business,

with thermocompression bonding achieving record revenue and orders. Besi also stated that the adoption of hybrid bonding continues to advance, showing that high-end packaging equipment is becoming an important source of revenue and profit improvement. From the perspective of outsourced semiconductor assembly and test companies, ASE is focusing its capital expenditure on advanced packaging and testing, while Amkor also regards advanced packaging and computing-related business as growth directions. This means downstream customers will continue to purchase full-line equipment with higher precision, higher automation, and lower defect rates. Major industry trends also include supply chain regionalization and policy-driven development. The U.S. CHIPS advanced packaging program emphasizes domestic advanced packaging capabilities, while the EU Chips Act highlights supply chain resilience and reduced external dependence. These factors will encourage equipment companies to strengthen local services, delivery capabilities, and process collaboration. Therefore, future industry competition will no longer be limited to the performance of individual machines, but will revolve around advanced packaging process coverage, customer qualification cycles, software control, yield improvement, and global delivery capabilities.

This report studies the global Semiconductor Automatic Packaging Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Semiconductor Automatic Packaging Equipment and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Semiconductor Automatic Packaging Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study
Global Semiconductor Automatic Packaging Equipment total production and demand, 2021-2032, (Units)
Global Semiconductor Automatic Packaging Equipment total production value, 2021-2032, (USD Million)
Global Semiconductor Automatic Packaging Equipment production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Units), (based on production site)
Global Semiconductor Automatic Packaging Equipment consumption by region & country, CAGR, 2021-2032 & (Units)
U.S. VS China: Semiconductor Automatic Packaging Equipment domestic production,

consumption, key domestic manufacturers and share
Global Semiconductor Automatic Packaging Equipment production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Units)
Global Semiconductor Automatic Packaging Equipment production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Units)
Global Semiconductor Automatic Packaging Equipment production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Units)

This report profiles key players in the global Semiconductor Automatic Packaging Equipment market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include BESI, Pentamaster, ASMPT, Sempro, Micro Modular System, Powertrim Technologies, Samil Tech, Tonitec, Genesem, Towa Japan, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Semiconductor Automatic Packaging Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$ Millions), volume (production, consumption) & (Units) and average price (K US$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Semiconductor Automatic Packaging Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Semiconductor Automatic Packaging Equipment Market, Segmentation by Type:

Wafer Dicing Saws

Die Bonder

Wire Bonder

Molding Equipment

Plating Equipment

Others

Global Semiconductor Automatic Packaging Equipment Market, Segmentation by Throughput/UPH:

?3,000 UPH

3,000–10,000 UPH

10,000–30,000 UPH

?30,000 UPH

Global Semiconductor Automatic Packaging Equipment Market, Segmentation by Package Type:

- DIP Packaging Equipment
- SOP Packaging Equipment
- SSOP Packaging Equipment
- TSSOP Packaging Equipment
- QFP Packaging Equipment
- QFN Packaging Equipment
- Others

Global Semiconductor Automatic Packaging Equipment Market, Segmentation by Application:

- Consumer Electronics
- Automotive
- Industrial
- Medical
- Communication
- Others

Companies Profiled:

- BESI
- Pentamaster
- ASMPT

Sempro

Micro Modular System

Powertrim Technologies

Samil Tech

Tonitec

Genesem

Towa Japan

Yamaha Robotics

Applied Materials

Kulicke and Soffa Industries

Palomar Technologies

Toray Engineering

Takatori Corporation

Mtex Matsumura

Guangdong Taijin Semiconductor Technology

Anhui Nextool Technology

Dalian Taiee Semiconductor Equipment

WenYi Trinity Technology (Anhui)

CINCY INTELLIGENT (DONGGUAN)

Jiangsu National Chip Intelligent Equipment

Key Questions Answered:
1. How big is the global Semiconductor Automatic Packaging Equipment market?
2. What is the demand of the global Semiconductor Automatic Packaging Equipment market?
3. What is the year over year growth of the global Semiconductor Automatic Packaging Equipment market?
4. What is the production and production value of the global Semiconductor Automatic Packaging Equipment market?
5. Who are the key producers in the global Semiconductor Automatic Packaging Equipment market?
6. What are the growth factors driving the market demand?

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